

The evolution of TDK 45nm Clean Technology

All-out, full on clean performance Reliable, Dependable Design

A large, white, industrial-grade machine with a top-loading door that is open, revealing internal components. The machine is set against a dark background with vibrant, glowing blue and purple light trails. A large, dark circular graphic is overlaid on the right side of the image, containing the product name in white text.

FOUP
Load Port
TAS300
Type-E4

FOUP Load Port TAS300 Type-4

1. The highest degree of cleanness ever achieved in the industry

The number of microscopic particles reduced to the absolute minimum. The world's highest ever recorded level in a PWP test

- Designed to keep a unit thoroughly clean – the wiring and piping do not come into contact whilst the equipment is in operation.
- TDK's unique precision control air flow

2. High compatibility – compatible with the FOUP of every company

A unique mechanism, highly adaptable to the smallest difference in each FOUP, prevents any impact between the FOUP and the load port; secure and reliable latch key insertion gives high compatibility.

- Air cushion system: ensures secure and reliable attachment and removal, opening and closing with the FOUP of each company.
- Introduction result: world share No.1* * Since the start of sales in 2001, over 10,000 units sold (as of November 2005)

3. Improvements to maintenance

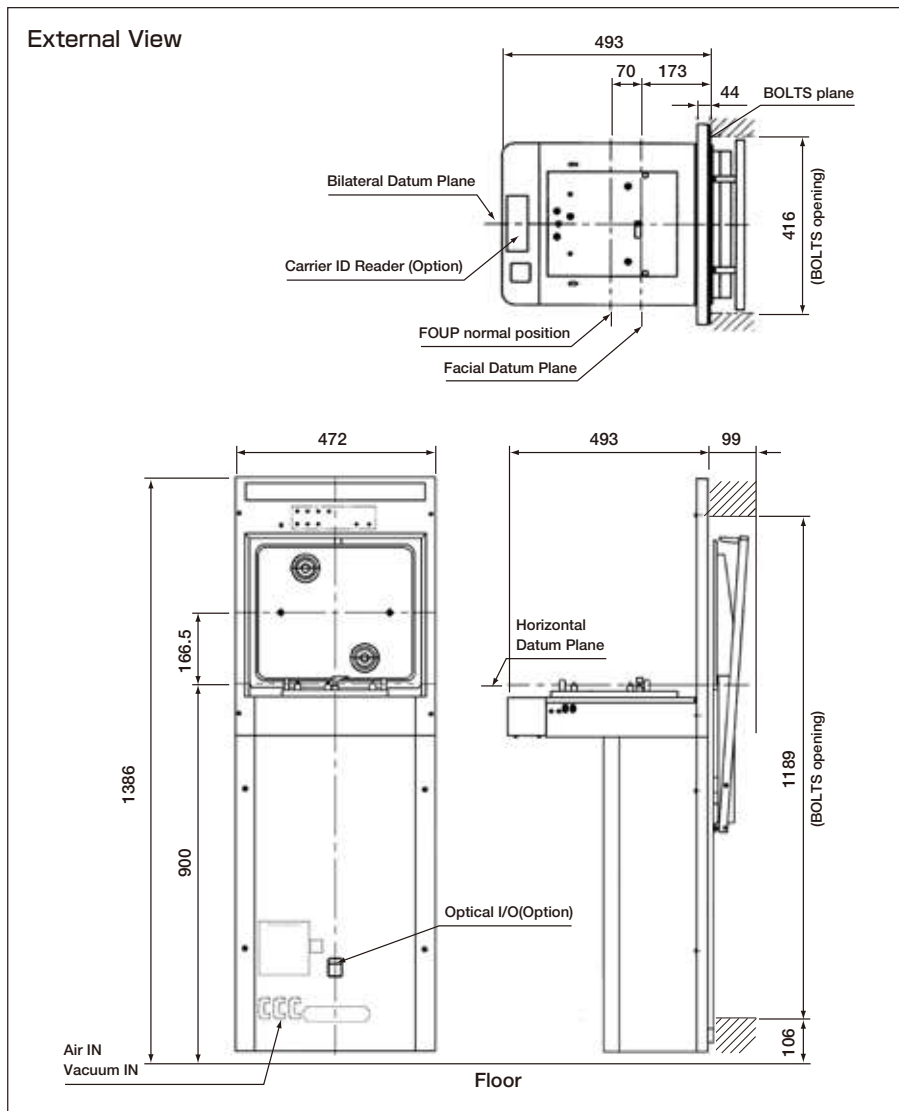
Designed for easy maintenance: maintenance in the minimum of time; the unit can without difficulty be quickly customized for any semiconductor production line.

- 50% time saving over earlier version: installation time into semiconductor manufacturing equipment and time for regular maintenance, including parts replacement slashed by more than half.

4. High reliability and high durability

TDK's factory automation technology ensures excellent reliability, stability and durability.

- A highly reliable design; outstanding results in reliability tests, decrease in the number of drive shafts.
- MCBF* 500,000 times achieved *MCBF – Mean Cycle Between Failure: the number of operations of a piece of equipment from the start of use or after repair of a malfunction, until the next equipment failure



SPECIFICATIONS

Machine Capacity

Presence of FOUP

FOUP normal of position

Detection Function

Prevents hand front being caught

FOUP docking

Wafer flying out

FOUP Door detection

Stroke

Y-axis(FOUP forward and back motion)

70mm(SEMI Standard)

Repeat accuracy

Y-axis(FOUP forward and back motion)

±0.1mm

Operation time

FOUP open operation;10sec.

FOUP close operation;10sec.

Suitable Product Specifications

300mm FOUP(SEMI E47.1,E62 compliant product)

Options

N2 Purge

Front Purge

Bottom Purge

Hybrid Purge

Details available on request.



Read the operation manual and precautions thoroughly for safety handling before actually using it.



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